UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/709,752	05/26/2004	Kohichi Ohsumi	JP920030018US1	3751
	7590 08/25/200 NAL BUSINESS MAC	EXAMINER		
DEPT. 18G		CHANG, RICK KILTAE		
BLDG. 321-482 2070 ROUTE 5		ART UNIT	PAPER NUMBER	
HOPEWELL JU	UNCTION, NY 12533	3726		
			NOTIFICATION DATE	DELIVERY MODE
			08/25/2009	ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

EFIPLAW@US.IBM.COM

		Application No.	Applicant(s)		
Office Action Summary		10/709,752	OHSUMI ET AL.		
		Examiner	Art Unit		
		Rick K. Chang	3726		
The MAILING DATE of this o Period for Reply	ommunication appe	ars on the cover shee	t with the correspondence a	ddress	
A SHORTENED STATUTORY PE WHICHEVER IS LONGER, FROM - Extensions of time may be available under the after SIX (6) MONTHS from the mailing date o - If NO period for reply is specified above, the m - Failure to reply within the set or extended perio Any reply received by the Office later than thre earned patent term adjustment. See 37 CFR	THE MAILING DA- provisions of 37 CFR 1.136 this communication. aximum statutory period will d for reply will, by statute, ce months after the mailing d	TE OF THIS COMMU (a). In no event, however, ma apply and will expire SIX (6) ause the application to becom	JNICATION. ay a reply be timely filed MONTHS from the mailing date of this ne ABANDONED (35 U.S.C. § 133).		
Status					
Responsive to communication This action is FINAL . Since this application is in concluded in accordance with the conclusion.	2b)∏ This a andition for allowand	ection is non-final. se except for formal n	•	e merits is	
Disposition of Claims					
4) Claim(s) 1-13 and 15-20 is/a 4a) Of the above claim(s) 1-4 5) Claim(s) is/are allowe 6) Claim(s) 5-13 is/are rejected 7) Claim(s) is/are objecte 8) Claim(s) are subject to	<u>and 15-20</u> is/are w d. ed to.	ithdrawn from consic			
<u>_</u>					
9) The specification is objected 10) The drawing(s) filed on Applicant may not request that a Replacement drawing sheet(s) is 11) The oath or declaration is obj	_ is/are: a) ☐ accep any objection to the dr ncluding the correctio	oted or b) objected awing(s) be held in about the drawing is required if the draw	eyance. See 37 CFR 1.85(a). ving(s) is objected to. See 37 C	, ,	
Priority under 35 U.S.C. § 119					
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing B 3) Information Disclosure Statement(s) (PTO Paper No(s)/Mail Date 5/19/09.		Paper 5) I Notice	ew Summary (PTO-413) No(s)/Mail Date of Informal Patent Application 		

Art Unit: 3726

DETAILED ACTION

Election/Restrictions

1. Newly submitted claims 1-4 and 15-20 are directed to an invention that is independent or distinct from the invention originally claimed for the following reasons: claims 1-4 require selectively forming a plating layer on at least one area of said up surface of said metal foil; adjusting a thickness of said plating layer; forming a resist pattern on areas of said up surface of said metal foil not covered by said plating layer after said plating layer being selectively formed. Claims 15-20 require removing said first resist pattern, thereby exposing said metal foil underneath said first resist pattern, and forming a second resist layer on top of said plating layer and said exposed metal foil, said second resist layer having a second resist pattern on areas of said exposed metal foil previously covered by said first resist pattern; and forming areas of said exposed metal foil previously covered by said first resist pattern into one or more conductive lines, said one or more conductive lines being separated from areas of said metal foil covered by said plating layer. On the other hand, claims 5-13 require forming an opening in said metal foil and said insulating substrate; forming a first resist pattern on said metal foil; forming a plating layer on an inner surface of said opening and areas of an up surface of said metal foil not covered by said first resist pattern; adjusting a thickness of said plating layer on said metal foil; and forming areas of said up surface of said metal foil not covered by said plating layer into one or more lines, said one or more lines being separated from said areas of said up surface covered by said plating layer and including a portion of said up surface.

Since applicant has received an action on the merits for the originally presented invention, this invention has been constructively elected by original presentation for prosecution

Art Unit: 3726

on the merits. Accordingly, claims 1-4 and 15-20 are withdrawn from consideration as being directed to a non-elected invention. See 37 CFR 1.142(b) and MPEP § 821.03.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 5-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579) in view of Hirose et al (US 6,591,495).

Re claim 5: Larson discloses preparing an insulating substrate (10) having a front surface and a back surface, and a layer of metal foil (12) formed on at each one of said front surface and said back surface, said metal foil having an up surface (above 12 in Fig. 1A); selectively forming or forming an opening (a through hole in Fig. 1A) in a metal foil of one of said metal foils and said insulating substrate; forming a first resist pattern (16) on said metal foil; forming a plating layer (18) on an inner surface of said opening and areas of an up surface of said metal foil not covered by said first resist pattern; adjusting a thickness of said plating layer on said metal foil (col. 4, line 52), except for forming areas of said up surface of said metal foil not covered by said plating layer into one or more lines, said one or more lines being separated from said area of said up surface covered by said plating layer and including a portion of said up surface.

Hirose disclose forming areas of said up surface of said metal foil not covered by said plating layer into one or more lines, said one or more lines being separated from said area of said up surface covered by said plating layer and including a portion of said up surface (88).

It would have been obvious to one of ordinary skill in the art at the time the invention ade to modify Larson by forming areas of said up surface of said metal foil not covered by

Page 4

was made to modify Larson by forming areas of said up surface of said metal foil not covered by said plating layer into one or more lines, said one or more lines being separated from said area of said up surface covered by said plating layer and including a portion of said up surface, as taught by Hirose, for the purpose of forming a multilayered printed circuit board.

Re claim 6: Larson discloses removing said first resist pattern (16 removed in Fig. 1I); forming a second resist pattern (20,22) on said areas of said metal foil; selectively forming an exposed portion of said areas of said metal foil using said second resist pattern (Fig. 1I); etching said metal foil at said exposed portion (12,14 removed); and removing said second resist pattern (20 removed).

4. Claim 7 is rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579)/Hirose et al (US 6,591,495) as applied to claims 5-6 above, and further in view of Shipley (US 4,902,610).

Larson/Hirose fail to disclose forming a dielectric layer on said insulating substrate and on said plating layer and said lines on said metal foil; forming an opening in said plating layer; and performing plating on said opening.

Shipley discloses forming a dielectric layer (3) on a substrate (2) and on said lines (1); forming an opening (openings above 1 in Fig. 2) in said dielectric layer on the land; and performing plating on said opening (6).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Larson/Hirose by forming a dielectric layer on said insulating substrate and on said plating layer and said lines on said metal foil; forming an opening in said plating layer;

Art Unit: 3726

and performing plating on said opening to the Larson/Hirose's PCB, as taught by Shipley, for the purpose of electrically communicating the inner circuits to the exterior circuits.

5. Claims 8-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579)/Hirose et al (US 6,591,495) as applied to claims 5-6 above, and further in view of Tamm et al (US 5,666,722).

Larson/Hirose fail to disclose polishing a surface of said plating layer.

Tamm discloses polishing a surface of said plating layer (Fig. 2f).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Larson/Hirose by polishing a surface of said plating layer to the Larson/Hirose's PCB, as taught by Tamm, for the purpose of meeting the electrical requirements of the final circuit.

6. Claim 10 is rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579)/Hirose et al (US 6,591,495)/Shipley (US 4,902,610) as applied to claims 5-7 above, and further in view of Tamm et al (US 5,666,722).

Larson/Hirose/Shipley fail to disclose polishing a surface of said plating layer.

Tamm discloses polishing a surface of said plating layer (Fig. 2f).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Larson/Hirose/Shipley by polishing a surface of said plating layer to the Larson/Hirose/Shipley's PCB, as taught by Tamm, for the purpose of meeting the electrical requirements of the final circuit.

Art Unit: 3726

7. Claims 11-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579)/Hirose et al (US 6,591,495)/Tamm et al (US 5,666,722) as applied to claims 5-6, 8-9 above, and further in view of Asai et al (US 6,828,510).

Larson/Hirose/Tamm fail to disclose polishing using a belt sander.

Asai discloses polishing using a belt sander (col. 23, line 49).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Larson/Hirose/Tamm by polishing using a belt sander to the Larson/Hirose/Tamm's PCB, as taught by Asai, for the purpose of meeting the electrical requirements of the final circuit.

8. Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Larson (US 5,160,579)/Hirose et al (US 6,591,495)/Shipley (US 4,902,610)/Tamm et al (US 5,666,722) as applied to claims 5-7, 10 above, and further in view of Asai et al (US 6,828,510).

Larson/Hirose/Shipley/Tamm fail to disclose polishing using a belt sander.

Asai discloses polishing using a belt sander (col. 23, line 49).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Larson/Hirose/Shipley/Tamm by polishing using a belt sander to the Larson/Hirose/Shipley/Tamm's PCB, as taught by Asai, for the purpose of meeting the electrical requirements of the final circuit.

Response to Arguments

9. Applicant's arguments filed 5/19/09 have been fully considered but they are not persuasive.

Application/Control Number: 10/709,752

Art Unit: 3726

In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., Page 8/11, lines 1-11) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Page 7

88 meets the limitation as stated in the rejection to claims 5-6. The examiner stated the rational for combining the references as stated above. The applicants failed to provide any reasons for Hirose not meeting the limitation.

Larson discloses preparing an insulating substrate (10) having a front surface and a back surface, and a layer of metal foil (12) formed on at each one of said front surface and said back surface, said metal foil having an up surface (above 12 in Fig. 1A); selectively forming or forming an opening (a through hole in Fig. 1A) in a metal foil of one of said metal foils and said insulating substrate; forming a first resist pattern (16) on said metal foil; forming a plating layer (18) on an inner surface of said opening and areas of an up surface of said metal foil not covered by said first resist pattern; adjusting a thickness of said plating layer on said metal foil (col. 4, line 52).

Interviews After Final

10. Applicant note that an interview after a final rejection must be submitted briefly in writing the intended purpose and content of the interview (the agenda of the interview must be in writing). Upon review of the agenda, the Examiner may grant the interview if the examiner is convinced that disposal or clarification for appeal may be accomplished with only nominal

Art Unit: 3726

further consideration. <u>Interviews merely to restate arguments of record or to discuss new</u> limitations will be denied. See MPEP 714.13 and 713.09.

Conclusion

- 11. Please provide reference numerals (either in parentheses next to the claimed limitation or in a table format with one column listing the claimed limitation and another column listing corresponding reference numerals in the remark section of the response to the Office Action) to all the claimed limitations as well as support in the disclosure for better clarity (optional). Applicants are duly reminded that a full and proper response to this Office Action that includes any amendment to the claims and specification of the application as originally filed requires that the applicant point out the support for any amendment made to the disclosure, including the claims. See 37 CFR 1.111 and MPEP 2163.06.
- 12. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Art Unit: 3726

13. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Rick K. Chang whose telephone number is (571) 272-4564. The

examiner can normally be reached on 5:30 AM to 1:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, David P. Bryant can be reached on (571) 272-4526. The fax phone number for the

organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published applications

may be obtained from either Private PAIR or Public PAIR. Status information for unpublished

applications is available through Private PAIR only. For more information about the PAIR

system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR

system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would

like assistance from a USPTO Customer Service Representative or access to the automated

information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Rick K. Chang/

Primary Examiner, A.U. 3726

RC

August 21, 2009